DELL ™ OPTIPLEX [™] 3010

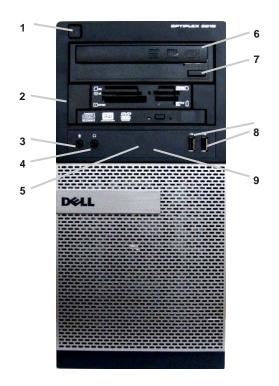
TECHNICAL GUIDEBOOK



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MINI TOWER COMPUTER (MT) VIEW



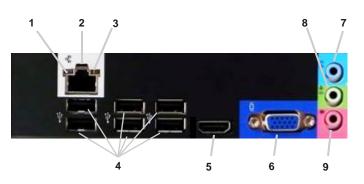
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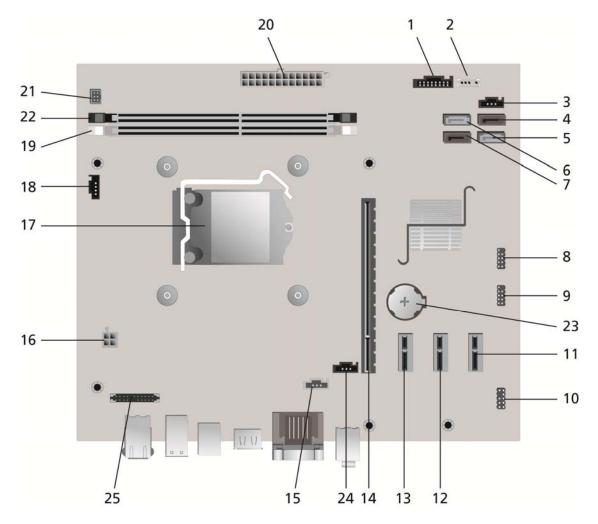
FRC	FRONT VIEW					
1	Power Button, Power Light	6	Optical Drive (optional)			
2	Optical Drive Bay (optional)	7	Optical Drive Eject Button			
3	Microphone Connector	8	USB 2.0 Connectors (2)			
4	Headphone Connector	9	Drive Activity Light			
5	Diagnostic Lights (4)					

3A(CK VIEW
LO	Power Supply [

10	Power Supply Diagnostic Light	14	Expansion Card Slots(4)
11	Power Supply Diagnostic Button	15	Security Cable Slot
12	Power Connectors	16	Padlock Ring
13	Back Panel Connectors		

BACK PANEL CONNECTORS					
1	Link Integrity Light	6	VGA Connector		
2	Network Connector	7	Line-in Connector		
3	Network Activity Light	8	Line-out Connector		
4	USB Connectors (6)	9	Microphone Connector		
5	HDMI Connector				

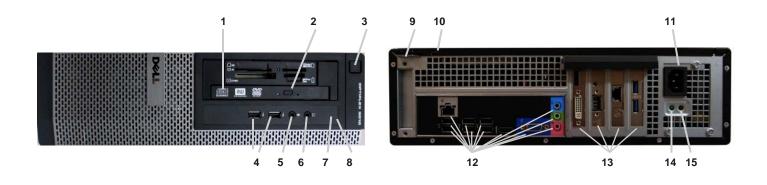




MT System Board Components

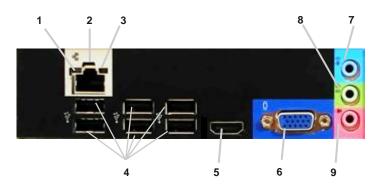
Number	Name	Number	Name
1	Front IO connector (LEDH1)	14	PCI-e 16x Connector (SLOT1)
2	Internal Speaker Connector (INT_SPKR1)	15	System fan Connector (FAN_SYS2)
3	System fan Connector (FAN_SYS1)	16	P2 Power Connector(ATX12V)
4	SATA 1 Connector(SATA1)	17	CPU Socket Connector (U27)
5	SATA 0 Connector(SATA0)	18	CPU fan Connector (FAN_CPU)
6	SATA 2 Connector(SATA2)	19	Memory Connector(DIMM1)
7	SATA 3 Connector(SATA3)	20	P1 power Connector (ATX)
8	Internal USB Connector (USBF2)	21	Power Switch Connector (PWRSW1)
9	Internal USB Connector (USBF1)	22	Memory Connector(DIMM2)
10	Internal Audio Connector (AUDIOF1)	23	Battery Connector (BT1)
11	PCI-e 1x Connector (SLOT4)	24	Intrusion Switch Connector (Intruder)
12	PCI-e 1x Connector (SLOT3)	25	KB/MS COM Connector (KBMSCOM1)
13	PCI-e 1x Connector (SLOT2)		

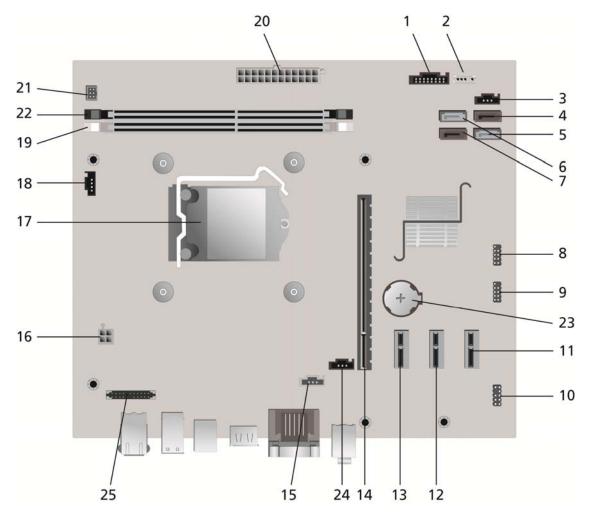
DESKTOP COMPUTER (DT) VIEW



FRONT VIEW			BACK VIEW				
1	Optical Drive	5	Microphone Connector	9	Padlock Ring	13	Expansion Card Slots(4)
2	Optical Drive Eject Button	6	Headphone Connector	10	Security Cable Slot	14	Power Supply Diagnostic Light
3	Power Button, Power Light	7	Drive Activity Light	11	Power Connectors	15	Power Supply Diagnostic Button
4	USB Connectors (2)	8	Diagnostic Lights (4)	12	Back Panel Connectors		

BACK PANEL CONNECTORS					
1	Link Integrity Light	6	VGA Connector		
2	Network Connector	7	Line-in Connector		
3	Network Activity Light	8	Line-out Connector		
4	USB Connectors (6)	9	Microphone Connector		
5	HDMI Connector				

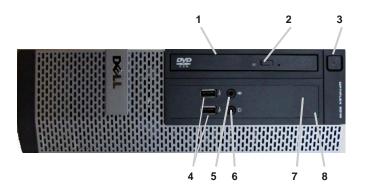


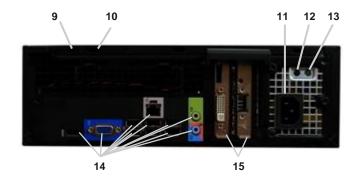


DT System Board Components

Number	Name	Number	Name
1	Front IO connector (LEDH1)	14	PCI-e 16x Connector (SLOT1)
2	Internal Speaker Connector (INT_SPKR1)	15	System fan Connector (FAN_SYS2)
3	System fan Connector (FAN_SYS1)	16	P2 Power Connector(ATX12V)
4	SATA 1 Connector(SATA1)	17	CPU Socket Connector (U27)
5	SATA 0 Connector(SATA0)	18	CPU fan Connector (FAN_CPU)
6	SATA 2 Connector(SATA2)	19	Memory Connector(DIMM1)
7	SATA 3 Connector(SATA3)	20	P1 power Connector (ATX)
8	Internal USB Connector (USBF2)	21	Power Switch Connector (PWRSW1)
9	Internal USB Connector (USBF1)	22	Memory Connector(DIMM2)
10	Internal Audio Connector (AUDIOF1)	23	Battery Connector (BT1)
11	PCI-e 1x Connector (SLOT4)	24	Intrusion Switch Connector (Intruder)
12	PCI-e 1x Connector (SLOT3)	25	KB/MS COM Connector (KBMSCOM1)
13	PCI-e 1x Connector (SLOT2)		

SMALL FORM FACTOR COMPUTER (SFF) VIEW

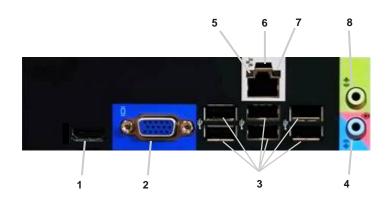


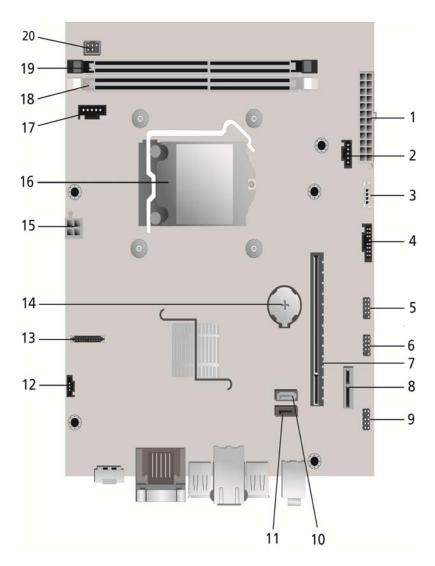


FRONT VIEW					
1	Optical Drive	5	Microphone Connector		
2	Optical Drive Eject Button	6	Headphone Connector		
3	Power Button, Power Light	7	Diagnostic Lights (4)		
4	USB 2.0 Connectors (2)	8	Drive Activity Light		

BA	CK VIEW		
9	Padlock Ring	13	Power Supply Diagnostic Light
10	Security Cable Slot	14	Back Panel Connectors
11	Power Connectors	15	Expansion Card Slots(2)
12	Power Supply Diagnostic Button		

BAC	BACK PANEL CONNECTORS					
1	HDMI Connector	5	Link Integrity Light			
2	VGA Connector	6	Network Connector			
3	USB Connectors (6)	7	Network Activity Light			
4	Line-in/Microphone Connector	8	Line-out Connector			





SFF System Board Components

Number	Name	Number	Name
1	P1 power Connector (ATX)	12	Intrusion Switch Connector (Intruder)
2	System fan Connector (FAN_SYS)	13	KB/MS COM Connector (KBMSCOM1)
3	Internal Speaker Connector (INT_SPKR1)	14	Battery Connector (BT1)
4	Front IO connector (LEDH1)	15	P2 Power Connector(ATX12V)
5	Internal USB Connector (USBF1)	16	CPU Socket Connector (U27)
6	Internal USB Connector (USBF2)	17	CPU fan Connector (FAN_CPU)
7	PCI-e 16x Connector (SLOT1)	18	Memory Connector(DIMM1)
8	PCI-e 1x Connector (SLOT2)	19	Memory Connector(DIMM2)
9	Internal Audio Connector (AUDIOF1)	20	Power Switch Connector (PWRSW1)
10	SATA 0 Connector(SATA0)		
11	SATA 1 Connector (SATA1)		

MARKETING SYSTEM CONFIGURATIONS

NOTE: Offerings may vary by country. For more information regarding the configuration of your computer, click Start>Help and Support and select the option to view information about your computer.

OPERATING SYSTEM

	МТ	DT	SFF		
Windows 7® operating system	Microsoft® Windows 7® Home Basic SP1 (32 and 64 bit), Microsoft® Windows 7® Home Premium SP1 (32 and 64 bit), Microsoft® Windows 7® Professional SP1 (32 and 64 bit), Microsoft® Windows 7® Ultimate SP1 (32 and 64 bit),				
Windows 8® operating system	Microsoft® Windows 8® (32 and 64 bit), Microsoft® Windows 8® Professional (32 and 64 bit),				
Other	Ubuntu® Linux (32bit)				
OS Media Support		Optional			

CHIPSET

	МТ	DT	SFF
Chipset Intel H61 Express Chipset			
Non-volatile memory on chipset			
BIOS Configuration SPI (Serial Peripheral Interface)	64Mbit (8MB) located at SPI_FLASH on chipset		
NIC EEPROM	LOM configuration contained within internal e-Fuse memory.		

PROCESSOR

NOTE: Global Standard Products (GSP) are a subset of Dell's relationship products that are managed for availability and synchronized transitions on a worldwide basis. They ensure the same platform is available for purchase globally. This allows customers to reduce the number of configurations managed on a worldwide basis, thereby reducing their costs. They also enable companies to implement global IT standards by locking in specific product configurations worldwide. The following GSP processors identified below will be made available to Dell customers.

NOTE: Processor numbers are not a measure of performance. Processor availability subject to change and may vary by region/ country.

МТ	DT	SFF		
Intel® Quad Core™ i5 Processors				
Х	Х	Х		
Х	Х	Х		
Х	Х	Х		
Х	Х	Х		
Х	Х	Х		
Х	Х	Х		
Х	Х	Х		
Х	Х	Х		
	X X X X X X X X	X X X X X X X X X X X X X X X X X X X X X X X X X X X X X X X X		

MEMORY

NOTE: Memory modules should be installed in pairs of matched memory size, speed, and technology. If the memory modules are not installed in matched pairs, the computer will continue to operate, but with a slight reduction in performance. The entire 8GB memory range is available to 64-bit operating systems.

МТ	DT	SFF
	1333 & 1600MHz ²	•
2	2	2
Up to 4GB	Up to 4GB	Up to 4GB
2GB	2GB	2GB
8GB ¹	8GB ¹	8GB ¹
Maximum System Memory 8GB ¹ 8GB ¹ Memory configurations 8GB ¹ 8GB ¹		
Х	Х	Х
Х	х	Х
Х	Х	Х
х	х	Х
Х	Х	Х
	2 Up to 4GB 2GB 8GB ¹ X X X X X X	1333 & 1600MHz ² 2 2 Up to 4GB Up to 4GB 2GB 2GB 8GB ¹ 8GB ¹ X X X X X X X X X X X X X X X X X X X X X X X X X X

1 To fully utilize 4GB or more of memory requires a 64-bit enabled processor and 64-bit operating system. With 32-bit OS, the total amount of available memory will be less than 4GB. The amount less depends on the actual system configuration.

2 1600MHz memory will perform as 1333MHz memory if Intel® 2nd generation Celeron, Pentium Dual Core™ or Core i3/i5 processors are installed in the system

HARD DRIVES

	МТ	DT	SFF
Bays:			
5.25-inch Optical Bay Supported (External)	2	1	1
Optical Drives Supported (maximum)	2	1	1 (slim-line)
Hard Drive Bay Supported (Internal)	2	1	1
Hard Drives Supported 3.5"(maximum)	2	1	1
Interface:	·		
SATA 2.0	4	4	2
SATA 3.0 (chipset does not support)			
3.5" Hard Drives:			
1TB ¹ SATA 7200 RPM HDD	Х	Х	Х
500GB ¹ SATA 7200 RPM HDD	Х	Х	Х
250GB ¹ SATA 7200 RPM HDD	Х	Х	Х

REMOVABLE STORAGE

	МТ	DT	SFF
Optical Drive: (SFF require slim-line optical drive)			
DVD+/-RW ² SATA 1.5Gbit/s	Х	Х	Х
DVD-ROM ³ SATA 1.5Gbit/s	Х	Х	Х
Media Card Reader: (requires slim line optical)			
Dell 19 in 1 Media Card Reader	Х	Х	

NOTE: Dell 19 in 1 Media Card Reader (MCR) is supported via a F5 to F3 bay converter on the MT and DT and may require a slim line optical drive depending on selectable configuration. MCR is not available on the SFF.

SYSTEM EXPANSION SLOTS

NOTE: See Detailed Engineering Specifications for maximum card dimensions.

NOTE: Add in card location and priority: PCIe x16: GFX, USB 3.0, Parallel/Serial, NIC, Wireless; PCIe x1: USB 3.0, Parallel/Serial, NIC, Wireless

NOTE: All PCIe slots support PCIe 2.0	МТ	DT	SFF
PCIe x16 Slot	1	1	1
PCIe x1 Slot	3	3	1
Serial ATA (SATA) connectors	4	4	2

COMMUNICATIONS - NETWORK ADAPTER (NIC)

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	МТ	DT	SFF
Integrated Realtek LOM	Integrated on system board		ard
Broadcom NetXtreme 10/100/1000 PCIe Gigabit ¹ Networking Card		Optional card	

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - WIRELESS

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	МТ	DT	SFF
Dell Wireless 1520 PCIe WLAN card (802.11n)		Optional card	
Dell Wireless 1530 PCIe WLAN card (802.11n) ¹		Optional card	

¹Available post launch

AUDIO AND SPEAKERS

	МТ	DT	SFF
Conexant CX20641 High Definition Audio Codec	Integrated on system board		
Internal Dell Business Audio Speaker	Optional		
Dell AX210 2.0 Desktop Speakers	Optional		
Dell AX510/AX510PA Flat Panel Soundbar Speakers	Optional		

	МТ	DT	SFF	
Dell USB Entry Keyboard with optional palmrest	Optional			
Dell Multimedia Pro Keyboard	Optional			
Dell USB Optical Mouse	Optional			
Dell Laser Mouse	Optional			

SECURITY HARDWARE

	МТ	DT	SFF
Chassis Intrusion Switch	Optional		
Chassis lock slot and loop support	Standard		

SECURITY SOFTWARE

	МТ	DT	SFF
Dell Data Protection Encryption (DDPE)		Optional	

ENVIRONMENTAL

NOTE: For more details on Dell Environmental features, please to go to Environmental Attributes section. See your specific region for availability.

	МТ	DT	SFF
Sustainable packaging	Х	Х	Х
MultiPack packaging	Optional, US only		
Energy Efficient Power Supply	Optional		

ALL-IN-ONE STANDS AND MOUNTS

	МТ	DT	SFF
Small Form Factor AIO Stand			Optional

SERVICE AND SUPPORT

NOTE: For more details on Dell Service Plans please to go to: <u>www.dell.com/service/service_plans</u>

	МТ	DT	SFF
3 Year Warranty ¹ Next Business Day On-site ² (3-3-3)	Standard		
ProSupport	Optional		

¹ For a copy of our guarantees or limited warranties, please write Dell USA L.P., Attn: Warranties, One Dell Way, Round Rock, TX 78682. For more information, visit www.dell.com/warranty.

² Service may be provided by third-party. Technician will be dispatched if necessary following phone-based troubleshooting. Subject to parts availability, geographical restrictions and terms of service contract. Service timing dependent upon time of day call placed to Dell. U.S. only.

DETAILED ENGINEERING SPECIFICATIONS

SYSTEM DIMENSIONS (PHYSICAL)

NOTE: System Weight and Shipping Weight is based on a typical configuration and may vary based on PC configuration. A typical configuration includes: integrated graphics, one hard drive, one optical drive.

	МТ	DT	SFF
Chassis Volume (liters)	26.27	15.06	8.38
Chassis Weight (pounds/kilograms)	19.55 / 8.87	16.67 / 7.56	12.57 / 5.70
Chassis Dimensions: (HxWxD)			
Height (inches/centimeters)	14.17 / 36	14.17 / 36	11.42 / 29
Width (inches/centimeters)	6.89 / 17.5	4.02 / 10.2	3.65 / 9.26
Depth (inches/centimeters)	16.42 / 41.7	16.14 / 41	12.28/31.2
Shipping Weight (pounds/kilograms - includes packaging materials)	23.45 / 10.64	20.03 / 9.09	15.2 / 6.89
Packaging Parameters (HxWxD)		-	-
Height (inches/centimeters)	21.31/54.13	21.31 / 54.13	19.25/48.90
Width (inches/centimeters)	18.75/47.63	18.75/47.63	15.81/40.16
Depth (inches/centimeters)	14.09 / 35.79	10.84/27.53	10.19/25.88

SYSTEM EXPANSION SLOTS

	МТ	DT	SFF
PCIe x16 Slots (Voltage supported 3.3V/12V)	1	1	1
Height (inches/centimeters)	4.376 / 11.115	2.731 /6.89	2.731 /6.89
Length (inches/centimeters)	6.6 /16.765	6.6 /16.765	6.6/16.765
Maximum Wattage	75W	50W	50W
PCIe x1 Slots (Voltage supported 3.3V/12V)	3	3	1
Height (inches/centimeters)	4.376 / 11.115	2.731 / 6.89	2.731 / 6.89
Length (inches/centimeters)	4.5 / 11.44	4.5 / 11.44	4.5 / 11.44
Maximum Wattage	10W	10W	10W

* Card length can be longer than standard Half-Length Card but cannot be a Full-Length Card.

GRAPHICS/VIDEO CONTROLLER

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	МТ	DT	SFF
Integrated Intel® HD Graphics 2500/4000 (3rd generation Core i3/i5 CPUs); Integrated Intel® HD Graphics 2000/3000 (2nd generation Core i3 CPUs); Integrated Intel® HD Graphics (Pentium® Dual Core and Celeron® CPUs)	Integrated on CPU		
Enhanced Graphic/Video Options			
1GB AMD RADEON HD7570 with DP and DVI	Optional FH card Optional LP card		
1GB AMD RADEON HD7470 with DP and DVI	Optional FH card	Optiona	l LP card

EXTERNAL PORTS/CONNECTORS

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards. See chassis diagrams section for port/ connector locations

	МТ	DT	SFF		
USB 2.0 (1 internal on MT and DT)		2 Front, 6 Rear			
Parallel and Serial port via optional PCIex1 card	Optional FH card				
Parallel port via optional PCIex1 card		Optiona	ILP card		
Serial and PS/2 via optional dongle	Optional FH card	Optiona	ILP card		
Network Connector (RJ-45)		1 Rear			
USB 3.0 via optional PClex1 card	Optional FH card	Optional FH card Optional LP card			
Video:					
VGA		1 Rear			
HDMI		1 Rear			
Audio:					
Line in for microphone		1 Front, 1 Rear			
Line in for stereo	1 Rear				
Line out for headphones or speakers		1 Front, 1 Rear			

SYSTEM LEVEL ENVIRONMENTAL AND OPERATING CONDITIONS

	МТ	DT	SFF
Temperature			
Operating	10° te	o 35° C (50° to	95° F)
Non-Operating (Storage)	-40° tc	o 65° C (-40° to	149° F)
Relative Humidity	20% to 80% (non-condensing)		
Maximum vibration			
Operating	0.25 G at 3 f	to 200 Hz at 0.	5 octave/min
Non-Operating	0.5 G at 3 to 200 Hz at 1 octave/min		
Maximum Shock			
Operating		-sine pulse wit 50.8 cm/sec (20	
Non-Operating		square wave w 08 cm/sec (20	
Maximum Altitude			
Operating	-15.2 to 3	3048 m (–50 to	> 10,000 ft)
Non-Operating	-15.2 to 10	0,668 m (–50 t	o 35,000 ft)

POWER

NOTE: These form factors utilize a more efficient Active Power Factor Correction (APFC) power supply. Dell recommends only Universal Power Supplies (UPS) based on Sine Wave output for APFC PSUs, not an approximation of a Sine Wave, Square Wave, or quasi-Square Wave. If you have questions, please contact the manufacture to confirm the output type.

	۸ APFC	AT EPA	DT APFC EPA		_	
Dewer Supply Wetters	275W	275W High	250W	250W High	240W	240W High
Power Supply Wattage	2/5//	Efficiency	25000	Efficiency	24000	Efficiency
AC input Voltage Range	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac
AC input current (low ac range/high AC range)	5.0A / 2.5A	5.0A / 2.5A	4.4A / 2.2A	4.4A / 2.2A	4.0A / 2.0A	4.0A / 2.0A
AC input Frequency	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ
AC holdup time (80% load)	16 mini sec	16 mini sec	16 mini sec	16 mini sec	16 mini sec	116 mini sec
Average Efficiency (Energy Star 5.0 Compliant)		87 – 90 – 87% @ 20 – 50 – 100% load		87 - 90 - 87% @ 20 - 50 - 100% load		87 - 90 - 87% @ 20 - 50 - 100% load
Typical Efficiency (Active PFC)	65%		65%		65%	
DC parameters						
+3.3v output	10.0A	10.0A	7.0 A	7.0 A	3.5A	3.5A
+5.0v output	13A	13A	15A	15A	11A	11A
+12.0v output	12VA/17A; 12VB/10A	12VA/17A; 12VB/10A	17.8A	17.8A	17A	17A
+5.0v auxiliary output	4.0A	4.0A	4.0A	4.0A	4.0A	4.0A
-12.0v output	0.5A	0.5A	0.5A	0.5A	0.5A	0.5A
Max total power Max combined +3.3v / +5.0v power	275W 100W	275W 100W	255W 90W	255W 90W	235W 60W	235W 60W
Max combined 12.0v pow- er (note: only if more than one 12v rail)	240W	240W	N/A	N/A	N/A	N/A
BTUs/h (based on PSU max wattage)	938 BTU	938 BTU	853 BTU	853 BTU	819 BTU	819 BTU
Power Supply Fan	80*25mm	80*25mm	80*20/25mm	80*20/25mm	60*25mm	60*25mm
Compliance:			-	-		
Erp Lot6 Tier 2 0.5 watt requirement	Yes	Yes	Yes	Yes	Yes	Yes
Blue Angel Compliant	Yes	Yes	Yes	Yes	Yes	Yes
Climate Savers / 80Plus Compliant	No	Yes	No	Yes	No	Yes
FEMP (CECP) Standby Power Compliant	Yes	Yes	Yes	Yes	Yes	Yes

POWER

NOTE: These form factors utilize a more efficient Active Power Factor Correction (APFC) power supply. Dell recommends only Universal Power Supplies (UPS) based on Sine Wave output for APFC PSUs, not an approximation of a Sine Wave, Square Wave, or quasi-Square Wave. If you have questions, please contact the manufacture to confirm the output type.

3.0v CMOS battery (Type and estimated battery life)						
Brand	Туре	Voltage	Composition	Life		
JHT	CR2032	3V	Lithium	Continuous Discharge Under 15 kΩ Load to 2.0V End- Voltage. 20°C±2°C.940Hrs. or Longer.910Hrs.or Longer after 12 months. 0°C±2°C. 850Hrs. or Longer.820Hrs.or Longer after 12 months.		
MITSUBISHI	CR2032	3V	Lithium	Continuous Discharge Under 15 kΩ Load to 2.0V End- Voltage. 20°C±2°C.940Hrs. or Longer.910Hrs.or Longer after 12 months. 0°C±2°C. 850Hrs. or Longer.820Hrs.or Longer after 12 months.		

AUDIO

INTEGRATED CONEXANT CX20641 HIGH DEFINITION AUDIO	МТ	DT	SFF	
High Definition Stereo support	Х	Х	Х	
Number of channels	5.1	5.1	2	
Number of Bits / Audio resolution	16, 20), and 24-bit re	solution	
Sampling rate (recording/playback)	Support 44.	1K/48K/96K/19 rates	92 kHz sample	
Signal to Noise Ratio	98 dB DAC	98 dB DAC outputs, 90 dB for ADC in- puts		
Analog Audio	Х	Х	Х	
Dolby Digital				
ТНХ				
Digital out (S/PDIF)				
Audio Jack Impedance				
Microphone	4	0K ohm~60K d	ohm	
Line-In	4	40K ohm~60K ohm		
Line-Out		100~150 ohm		
Headphone		1~4 ohm		
Internal Speaker Power Rating	2Watt	2Watt (peak) / 1Watt (average)		

COMMUNICATIONS - NETWORK ADAPTER (NIC)

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

INTEGRATED REALTEK® RTL8111E-VL ETHERNET LAN 10/100/1000	MT DT SFF			
External Connector Type		RJ45		
Data Rates supported		10/100/1000 Mbr	os	
Controller Details				
Controller bus architecture	PCIe-based interface for S0 state, SMBus for low power state			
Integrated memory	N/A			
Data transfer mode (example Bus-Master DMA)	N/A			
Power consumption (full operation per data rate connection speed)		448.8mW (Max.)		
Power consumption (standby operation)	389.4mW (Max.)			
IEEE standards compliance (example 802.1P)		802.3		
Hardware Certifications (example FCC, B, GS mark)	N/A			
Boot ROM Support	EEPROM (located in SPI)			
Network Transfer Mode (example Full Duplex, Half Duplex)				
Network Transfer Rate (example 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	10 Mb (full/half-duplex) 100 Mb (full/half-duplex) 1000 Mb (full-duplex)			

COMMUNICATIONS - NETWORK ADAPTER (NIC) (CONT.)

INTEGRATED REALTEK® RTL8111E-VL ETHERNET LAN 10/100/1000	MT DT SFF				
Environmental					
Operating temperature	0° C to 70° C (32° F to 158° F)				
Operating humidity	20% to 80% (non-condensing)				
Operating System Driver Support	Windows 7/8 32/64, Windows XP 32/64, Vista 32/64				
Manageability (examples WOL, PXE)	WOL, PXE 2.1				

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - NETWORK ADAPTER (NIC)

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

Broadcom NetXtreme 10/100/1000 PCIe Gigabit ¹ Networking Card	МТ	MT DT SFF				
Connector Type		RJ45				
Data Rates supported	10/100/10	00 Mbps Half/F	ull duplex			
Controller Details						
Controller bus architecture (example PCIe 1.0a x1)		PCIe c1.0a x1				
Integrated memory	64KE	Bytes RX, 8KByte	es TX			
Data transfer mode (example Bus-Master DMA)	E	Bus-Master DMA				
Power consumption (full operation per data rate connection speed)	2.84	2.84W (860mA @ +3.3V)				
Power consumption (standby operation)	L	Less than 300mW				
IEEE standards compliance (example 802.1P)	802.3,	802.3, 802.2, 802.3x, 802.1p				
Hardware Certifications (example FCC, B, GS mark)	F	FCC B, VCCI B, CE				
Boot ROM Support		No				
Network Transfer Mode (example Full Duplex, Half Duplex)						
Network Transfer Rate (example 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	100BASE-TX 100BASE-TX 1000BASE-	10BASE-T (full-duplex) 20 Mbps Max 100BASE-TX (half-duplex) 100 Mbp Max* 100BASE-TX (full-duplex) 200 MbpsM 1000BASE-T (full-duplex) 2000 Mbp Max* * Depends on the system environment				

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - INTEGRATED LAN (CONT.)

BROADCOM NETXTREME 10/100/1000 PCIE GIGABIT ¹ NETWORKING CARD (CONT.)	МТ	DT	SFF		
Environmental					
Operating temperature	0° C to 55° C (32° F - 131° F)				
Operating humidity	5% ~ 85% (non-condensing)				
Operating System Driver Support	Windows® 7,Windows® 8 (32 and 64 bit), Windows® 8 Professional (32 and 64 bit) Windows® XP, Windows Vista® Ulti- mate, Windows Vista® Business 32 bit/64 bit, Windows Vista Home Basic, Linux				
Manageability (examples WOL, PXE)	WOL, PXE2.1, ACPI				
Management Capabilities Alerting (example ASF 2.0)	None				

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and

COMMUNICATIONS – WIRELESS

DELL WIRELESS 1520 PCIE WLAN CARD (MT, DT, SFF) 802.11N/ DELL WIRELESS 1530* PCIE WLAN CARD (MT, DT, SFF) 802.11N	MT DT SF		SFF	
External Connector Type	Custor	n WLAN Antenna Co	onnector	
Controller Details				
Controller bus architecture		mpatible with the P on v1.1 (x1 lane) and		
WLAN standards supported	802.11	a, 802.11b, 802.11g,	802.11n	
802.11b Data Rates supported		11, 5.5, 2, 1 Mbps		
802.11a Data Rates supported	54, 48, 36, 24, 18, 12, 9, 6 Mbps			
802.11g Data Rates supported	54, 48, 36, 24, 18, 12, 9, 6 Mbps			
802.11n Data Rates supported	300, 270, 243, 240, 180, 150, 144, 135, 130, 120, 117 115.5, 90, 86.667, 72.2, 65, 60, 57.8, 45, 43.3, 30, 28 21.7, 15, 14.4, 7.2 Mbps			
Encryption	WEP 64-bit and 128-bit, TKIP, AES-CCMP 128-bit			
Operating temperature	0 to +70 °C			
Operating humidity	Max Operating Humidity 85 %			
Operating System Driver Support	Windows 7 32/64, Windows 8 32/64, Windows XP 32/64, Vista 32/64			

* Available post launch

Communications - USB 3.0 add-in card: NEC

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

USB 3.0 PORT PCIE ADD-IN CARD	МТ	DT	SFF	
Connector Type	PCI Express Gen. 2.0 X1			
Controller Details				
Controller bus architecture (example PCIe 1.0a x1)	PCI Express one lane (x1)			
Chipset	NEC µPD720200			
IO Ports	2 * USB3.0 port			
Power Consumption	Under 30 mA			
Connector		USB 3.0 A Type		
Full height USB3.0 add-in card	Optional			
Half height USB3.0 add-in card	Optional			
OS Support	NEC :Win XP, Win Vista and Win 7			

COMMUNICATIONS - USB 3.0 ADD-IN CARD: IOI

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

USB 3.0 PORT PCIE ADD-IN CARD	МТ	DT	SFF	
Connector Type	PCI Express Gen. 2.0 X1			
Controller Details				
Controller bus architecture (example PCIe 1.0a x1)	PCI Express one lane (x1)			
Chipset	Etron EJ168A			
IO Ports	2 * USB3.0 port			
Power Consumption	Under 30 mA			
Connector		USB 3.0 A Type		
Full height USB3.0 add-in card	Optional			
Half height USB3.0 add-in card	Optional			
OS Support	Win XP, Win 7and Win 8			

COMMUNICATIONS - SERIAL / PARALLEL PORT PCIE ADD-IN CARD

NOTE: MT supports full height (FH) card, and DT and SFF supports low profile (LP) dongle.

SERIAL / PARALLEL PORT PCIE ADD-IN CARD	МТ	DT	SFF			
Connector Type	RS-232 and IEEE1284					
Data Rates supported	50bps ~115.2Kbps (Serial) &Maximum 1.8MBp(Parallel)					
Controller Details						
Controller bus architecture (example PCIe 1.0a x1)	PCI Express Spec 2.0, Single-Lane (x1)					
Driver Support	Microsoft Client XP/Vista/7/8(X86/X64) Microsoft Server 2000/2003/2008/2008 R2 (X86/X64) Microsoft Embedded XP Embedded/POS Ready 2009/ Embedded System 2009 Linux 2.4.x/2.6.x/3.x DOS					
Full height Serial / Parallel add-in card	Optional					
Environment	Environment					
Operation Temperature	0 to 60°C (32 to 140°F)					
Operation Humidity	5 to 95% RH					
Storage Temperature	-20 to 85°C (-4 to 185°F)					

COMMUNICATIONS - SERIAL / PARALLEL PORT PCIE ADD-IN CARD

NOTE: MT supports full height (FH) card, and DT and SFF supports low profile (LP) dongle.

LOW PROFILE PARALLEL PORT PCIE ADD-IN CARD	МТ	MT DT SFF					
Connector Type		IEEE1284					
Data Rates supported		Maximum 1.8MBp					
Controller Details							
Controller bus architecture (example PCIe 1.0a x1)	PCI Expr	PCI Express Spec 2.0, Single-Lane (x1)					
Driver Support	Microsoft Server Microsoft Embed	Microsoft Client XP/Vista/7/8(X86/X64) Microsoft Server 2000/2003/2008/2008R2 (X86/X64) Microsoft Embedded XP Embedded/POS Ready 2009 Embedded System 2009 Linux 2.4.x/2.6.x/3.x DOS					
Low Profile Parallel add-in card		Optic	onal				
Environment	Environment						
Operation Temperature	0 to 60°C (32 to 140°F)						
Operation Humidity 5 to 95% RH							
Storage Temperature	-2	-20 to 85°C (-4 to 185°F)					

COMMUNICATIONS - PS2/SERIAL ADD IN DONGLE

PS2/SERIAL ADD IN DONGLE	МТ	DT	SFF	
Connector type		RS232 and PS2		
Controller Details				
Interface type	24 pins	header connect to M	1B directly	
IO Ports	1 Serial, 2 PS2			
Full height PS2/Serial add in dongle	Optional			
Half height PS2/Serial add in dongle		Optional		
Environment				
Operation Temperature	0°	C to 70° C (32° F to 1	58° F)	
Operation Humidity	20% to 80% (non-condensing)			
Storage Temperature	-20 to 85°C (-4 to 185°F)			

GRAPHICS/VIDEO CONTROLLER

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	r		
Onboard Graphics: Integrated Intel® HD Graphics 2500/4000 (3rd generation Core i3/i5 CPUs); Integrated Intel® HD Graphics 2000/3000 (2nd generation Core i3 CPUs); Integrated Intel® HD Graphics (Pentium® Dual Core and Celeron® CPUs)	мт	DT	SFF
Bus Type		Integrated	
GPU core clock	Gen6 Core Intel® HD Graphics /HD Graphics 2000 @ 850MHz Gen7 Core Intel® HD Graphics 2500 / 4000 @ 650MHz		Ζ.
Frame Buffer Memory (onboard and shared) Size and Speed		vailable system r ith 4GB system I	
Overlay Planes		Yes	
Maximum Color Depth	32 bit		
Maximum Vertical Refresh Rate	75 Hz		
Multiple Display Support	Yes		
Operating Systems Graphics/ Video API Support	2nd gen Core CPUs OpenGL 3.0/DirectX 10.1 3rd gen Core CPUs OpenGL 3.0/DirectX 11		
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	Up to 1920x1200 @ 60Hz (HDMI) Up to 2048x1536 @ 75Hz (VGA)		
External Connectors	VGA, HDMI		
НДМІ			
Bus Type DDPD			
Maximum supported resolution Up to 1920x1200 @ 60H		60Hz	
Maximum power consumption N/A			
Audio Support	Yes (Only for native HDMI Output)		
External connectors HDMI			

¹Up to 1.7 GB of system memory may be allocated to support integrated graphics, depending on operating system, system memory size and other factors. ² DVI and VGA can be used concurrently for multi-monitor display in DOS. The DisplayPort controller does not support multi-monitor display in

DOS

GRAPHICS/VIDEO CONTROLLER (CONT.)

1GB AMD RADEON™ HD7570	мт	DT	SFF
Bus Type (example integrated or PCIe x16)	PCIEx16		
GPU core clock		650Mhz	
Frame Buffer Memory (onboard and shared) Size and Speed		800Mhz	
Maximum power consumption		50W	
Overlay Planes		Yes	
Maximum Color Depth		32-bit	
Maximum Vertical Refresh Rate		85Hz	
Multiple Display Support	Yes		
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	Dual-Link DVI Max: 2560 x 1600/32bpp @ 75Hz DispalyPort Max: 2560 x 1600/32bpp @ 75Hz Min : 640x480/8bpp @ 60Hz		2bpp @ 75Hz
External connectors	1 DVI-I and 1 DP		
Audio Support	Yes (For native DP). Able to support audio for DP to HDMI dongle that supports audio pass through.		
Dimensions of full height card inches/centimeters (L x H)	6.6 x 4.7 / 16.764 x 12.0		
Dimensions of low profile card inches/centimeters (L x H)	6.6 x 3.35 / 16.764 x 8.5		6.764 x 8.5
Environmental Operating Conditions (Non-Condensing):			
Operating Temperature Range	10°-50° C		
Relative Humidity Range	5-90% RH		
Altitude Range	0-20,000 ft.		

1GB AMD RADEON™ HD7470	МТ	DT	SFF
Bus Type (example integrated or PCIe x16)	PCIEx16		
GPU core clock		775Mhz	
Frame Buffer Memory (onboard and shared) Size and Speed		900Mhz	
Maximum power consumption		25W	
Overlay Planes		Yes	
Maximum Color Depth		32-bit	
Maximum Vertical Refresh Rate	85Hz		
Multiple Display Support	Yes		
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	DVI Max : 2560 x 1600/32bpp @ 75Hz DispalyPort Max: 2560 x 1600/32bpp @ 75Hz Min : 640x480/8bpp @ 60Hz		
External connectors	1 DVI-I and 1 DP		
Audio Support	Yes (For native DP). Able to support audio for DP to HDMI dongle that supports audio pass through.		
Dimensions of full height card inches/centimeters (L x H)	6.6 x 2.731 / 16.764 x 6.936		
Dimensions of low profile card inches/centimeters (L x H)	6.6 x 2.731 / 16.764 x 6.936		
Environmental Operating Conditions (Non-Condensing):			
Operating Temperature Range	10°-50° C		
Relative Humidity Range	5-90% RH		
Altitude Range	0-20,000 ft.		

HARD DRIVES¹

3.5″ 1TB SATA 7200 RPM HDD		
Capacity (bytes)	1,000,204,886,016	
Dimensions inches (W x D x H)	5.87 x 4 x 1	
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)	
Internal buffer size	32 MB	
Average Seek Time	8.5 ms	
Rotational Speed	7200 rpm	
Logical Blocks	1,953,525,168	
Power Source		
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)	
Spin Up Current (reference only)	5V (1A) ,12V (2A)	
Environmental Operating Conditions (Non-Condensing):		
Temperature Range	5°C to 60°C	
Relative Humidity Range	20% to 80% non-condensing	
Maximum Wet Bulb Temperature	29 ⁰ C	
Altitude Range	-50 ft to 10000 ft	
Environmental Non-Operating Conditions (Non-Condensing):		
Temperature Range	-40°C to 65°C	
Relative Humidity Range	10% to 90% non-condensing	
Maximum Wet Bulb Temperature	38°C	
Altitude Range	-50 ft to 35000 ft	

¹ For hard drives, GB means 1 billion bytes ; actual capacity varies with preloaded material and operating environment and will be less.

HARD DRIVES¹ (CONT.)

3.5″ 500GB SATA 7200 RPM HDD		
Capacity (bytes)	500,107,862,016	
Dimensions inches (W x D x H)	5.87 x 4 x 1	
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)	
Internal buffer size	16 MB	
Average Seek Time	8.5 ms	
Rotational Speed	7200 rpm	
Logical Blocks	976,773,168	
Power Source		
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)	
Spin Up Current (reference only)	5V (1A) ,12V (2A)	
Environmental Operating Conditions (Non-Condensing):		
Temperature Range	5°C to 60°C	
Relative Humidity Range	20% to 80% non-condensing	
Maximum Wet Bulb Temperature	29ºC	
Altitude Range	-50 ft to 10000 ft	
Environmental Non-Operating Conditions (Non-Condensing):		
Temperature Range	-40°C to 65°C	
Relative Humidity Range	10% to 90% non-condensing	
Maximum Wet Bulb Temperature	38°C	
Altitude Range	-50 ft to 35000 ft	

¹ For hard drives, GB means 1 billion bytes ; actual capacity varies with preloaded material and operating environment and will be less.

HARD DRIVES¹ (CONT.)

3.5″ 250GB SATA 7200 RPM HDD		
Capacity (bytes)	250,059,350,016	
Dimensions inches (W x D x H)	5.87 x 4 x 1	
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)	
Internal buffer size	8 MB	
Average Seek Time	8.5 ms	
Rotational Speed	7200 rpm	
Logical Blocks	488,397,168	
Power Source	_	
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)	
Spin Up Current (reference only)	5V (1A) ,12V (2A)	
Environmental Operating Conditions (Non-Condensing):		
Temperature Range	5°C to 60°C	
Relative Humidity Range	20% to 80% non-condensing	
Maximum Wet Bulb Temperature	29 ⁰ C	
Altitude Range	-50 ft to 10000 ft	
Environmental Non-Operating Conditions (Non-Condensing):		
Temperature Range	-40°C to 65°C	
Relative Humidity Range	10% to 90% non-condensing	
Maximum Wet Bulb Temperature	38°C	
Altitude Range	-50 ft to 35000 ft	

¹ For hard drives, GB means 1 billion bytes ; actual capacity varies with preloaded material and operating environment and will be less.

OPTICAL DRIVES

DVD +/- RW ¹	МТ	DT	SFF
External Dimensions inches/ centimeters (Without Bezel – W x H x D)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)
Weight (max) pounds/kilograms	800g	800g	170g
Interface type and speed	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s
Disc Capacity	Standard	Standard	Standard
Internal buffer size	supplier dependent	supplier dependent	supplier dependent
Access Times (typical)	supplier dependent	supplier dependent	supplier dependent
Maximum Data Transfer Rates			
Writes	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD
Reads	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD
Power Source			
DC Power Requirements	12V, 5V	12V, 5V	5V
DC Current	1200mA (12V)/ 900mA (5V)	1200mA (12V)/ 900mA (5V)	1000mA
Environmental Operating Condition	ons (Non-Condensing):		
Operating Temperature Range	5C to 50C	5C to 50C	5C to 50C
Relative Humidity Range	20% to 80% RH	20% to 80% RH	20% to 80% RH
Maximum Wet Bulb Temperature	29C	29C	29C
Altitude Range	-200 to 3048	-200 to 3048	-200 to 3048
Environmental Non-Operating Co	nditions (Non-Condensing):	· · · · · ·	
Operating Temperature Range	-40C to 65C	-40C to 65C	-40C to 65C
Relative Humidity Range	5% to 95% RH	5% to 95% RH	5% to 95% RH
Maximum Wet Bulb Temperature	38C	38C	38C
Altitude Range	-200 to 10600m	-200 to 10600m	-200 to 10600m

¹ Discs burned with this drive may not be compatible with some existing drives and players; using DVD+R media provides maximum compatibility.

DVD-ROM	МТ	DT	SFF
External Dimensions inches/ centimeters (Without Bezel – W x H x D)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)
Weight (max) pounds/kilograms	750g	750g	165g
Interface type and speed	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s
Disc Capacity	Standard	Standard	Standard
Internal buffer size	supplier dependent	supplier dependent	supplier dependent
Access Times (typical)	supplier dependent	supplier dependent	supplier dependent
Maximum Data Transfer Rates			
Writes	N/A	N/A	N/A
Reads	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD

DELL[™] OPTIPLEX[™] 3010 TECHNICAL GUIDEBOOK - VER 1.3

OPTICAL DRIVES (CONT.)

DVD-ROM (CONT.)	МТ	DT	SFF	
Power Source	Power Source			
DC Power Requirements	12V, 5V	12V, 5V	5V	
DC Current	1200mA (12V)/ 900mA (5V)	1200mA (12V)/ 900mA (5V)	800mA	
Environmental Operating Condition	ons (Non-Condensing):			
Operating Temperature Range	5C to 50C	5C to 50C	5C to 50C	
Relative Humidity Range	20% to 80% RH	20% to 80% RH	20% to 80% RH	
Maximum Wet Bulb Temperature	29C	29C	29C	
Altitude Range	-200 to 3048m	-200 to 3048m	-200 to 3048m	
Environmental Non-Operating Co	Environmental Non-Operating Conditions (Non-Condensing):			
Operating Temperature Range	-40C to 65C	-40C to 65C	-40C to 65C	
Relative Humidity Range	5% to 95% RH	5% to 95% RH	5% to 95% RH	
Maximum Wet Bulb Temperature	38C	38C	38C	
Altitude Range	-200 to 10600m	-200 to 10600m	-200 to 10600m	

MEDIA CARD READER (MCR)

NOTE: Dell 19 in 1 Media Card Reader (MCR) is supported via a F5 to F3 bay converter on the MT and DT and may require a slim line optical drive depending on selectable configuration. MCR is not available on the SFF and USFF chassis.

19 IN 1 MEDIA CARD READER	MT/DT
External Dimensions inches/(centimeters) (With Bezel – W x H)	3.99/(10.13cm)/1.0/(2.54cm)
Weight (max) pounds/kilograms	~155g
Interface type and speed	USB 2.0, 480Mb/s
Media Supported (maximum capacity supported will vary by I	Flash Media Types)
Media Supported	CF I CF II Micro Drive (MD) Secure Digital (SD) SDHC Mini Secure Digital (mini-SD) Micro Secure Digital (Micro-SD)(with adapter) Multi Media Card (MCO) RS Multi Media Card (MMC) Multi Media Card (RS-MMC) Multi Media Card plus (MMC plus) RS Multi Media Card plus (RS-MMC plus) Multi Media Card Micro(MMC Micro) (with adapter) Memory Stick Pro (MS Pro) Memory Stick Pro Duo) Memory Stick Pro Duo (MS Pro Duo) Memory Stick Duo (MS-Duo) Memory Stick Micro(MS Micro)(M2) (with adapter) Smart Media (SM) xD
Support Specification Versions:	Compact Flash type I/II Version 4.0 Smart Media (SM) Specification 2003 Multi Media Card (MMC) Specification 4.2 Secure Digital (SD) 2.0 Memory Stick Pro (MS-PRO) Specification 1.02 Memory Stick (MS) Specification 1.43 xD Specification 1.2
Power Source	· · · · · · · · · · · · · · · · · · ·
Max Power Requirements	2.5W
Supply Voltage Range	4.75V ~ 5.25V
Power Consumption:	Standby less than 0.5mA @ 5.0VDC
Environmental Operating Conditions (Non-Condensing):	
Operating Temperature Range	5C to 50C
Relative Humidity Range	10% to 90% RH
Environmental Non-Operating Conditions (Non-Condensing	y):
Operating Temperature Range	-40C to 65C
Relative Humidity Range	5% to 95% RH

BIOS DEFAULTS

System Configuration	Integrated NIC:	Enabled
	SATA Operation:	AHCI
	Drives:	Enable (SATA-0, SATA-1, SATA-2, SATA- 3)
	SMART Reporting:	Disable
		Enable or Disable the integrated USB Controller for Boot Support, Front USB,
	USB Controller:	Rear Dual USB, Rear Quad USB
	Miscellaneous Devices:	
Video	Multi-Display:	Disable
Performance	Multiple Core Support:	All
	Intel® SpeedStep™:	Enable
	C States Control:	Enable
	HyperThread control:	Enable
	HDD Protection Support	Disable
Virtualization Support	Virtualization:	Enable
	VT for Direct I/O:	Enable
Security	Strong Password:	Disable
	Password Configuration:	Min/Max: 4/32
	Password Bypass:	Disable
	Password Changes:	Enable
	Computrace®:	Deactivate
	Chassis Intrusion:	Disable
	CPU XD Support:	Enable
Power Management	AC Recovery:	Power Off
	Auto On Time:	Disable
	Deep Sleep Control:	Disable
	Fan Control Override:	Disable
	Wake on LAN:	Disable
Maintenance	Service Tag:	Set by the factory
	Asset Tag:	Optional User Entry
	SERR Message:	Enable
POST Behavior	Numlock LED:	Enable
	Keyboard Errors:	Enable
	POST HotKeys:	Enable
	Fast Boot:	Thorough

CHASSIS ENCLOSURE & VENTILATION REQUIREMENTS

ENCLOSURE VENTILATION

If your enclosure has doors, they need to be of a type that allows at least 30% airflow through the enclosure (front and back).

ENCLOSURE MINIMUM CLEARANCE

Leave a 10.2 cm (4 in.) minimum clearance on all vented sides of the computer to permit the airflow required for proper ventilation.

RECOMMENDED ENCLOSURE

Do not install your computer in an enclosure that does not allow airflow. This restricts the airflow and impacts your computer's performance, possibly causing it to overheat.

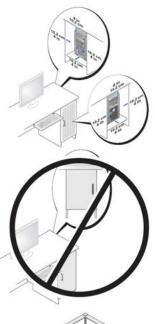
OPEN DESK MINIMUM CLEARANCE

If your computer is installed in a corner, on a desk, or under a desk, leave at least 5.1 cm (2 in.) clearance from the back of the computer to the wall to permit the airflow required for proper ventilation.

REGULATORY COMPLIANCE AND ENVIRONMENTAL

Product related conformity assessment and regulatory authorizations including Product Safety, Electromagnetic Compatibility (EMC), Ergonomics, and Communication Devices relevant to this product may be viewed at www.dell.com/ regulatory_compliance. The Regulatory Datasheet for this product is located at http://www.dell.com/regulatory_compliance.

Details of Dell's environmental stewardship program to conserve product energy consumption, reduce or eliminate materials for disposal, prolong product life span and provide effective and convenient equipment recovery solutions may be viewed at www.dell.com/environment. Product related conformity assessment, regulatory authorizations, and information encompassing Environmental, Energy Consumption, Noise Emissions, Product Materials Information, Packaging, Batteries, and Recycling relevant to this product may be viewed by clicking the Design for Environment link on the webpage.





ACOUSTIC NOISE EMISSION INFORMATION

OPTIPLEX 3010 MT

Component	Typical Configuration	High-end Configuration
CPU	Intel i5,3.1GHZ,4c SNB 95W	Intel i5,3.1GHZ,4c SNB 95W
Memory	4GB DDR3 1600MHz	4GB DDR3 1600MHz
HDD (#, capacity)	1TB 7200RPM SATA3	1TB 7200RPM SATA3(x2)
RMSD	16X DVD SATA HH 8X DVD+/-RW SATA 12.7	16X DVD SATA HH 8X DVD+/-RW SATA 12.7
Graphics Adapter	Intel [®] HD Graphics Family	ATI Redeon HD 7570

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 3010 MT is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})		
Idle	NA	3.2		
HDD Operating	NA	3.2		
80% TDP	NA	3.8		
ODD Operating	NA	4.1		

The Declared A-weighted Sound Pressure Level in decibels (re 2x10⁻⁵ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)				High-end Configuration Declared Sound Pressure (LpA)			
	Table-Top Floor-Standing			Table	е-Тор	Floor- Standing		
	Operator Position (LpA)	Bystander Position (LpA)	Opera- tor Posi- tion (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	NA	NA	NA	NA	22.9	19.1	18.0	18.8
HDD Operating	NA	NA	NA	NA	23.3	19.7	18.1	18.9
90% CPU	NA	NA	NA	NA	24.0	20.2	18.4	18.9
ODD Operating	NA	NA	NA	NA	43.6	36.8	36.6	35.3

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

ACOUSTIC NOISE EMISSION INFORMATION

OPTIPLEX 3010 DT

Component	Typical Configuration High-end Configuratio			
CPU	Intel i5,3.1GHZ,4c SNB 95W	Intel i5,3.1GHZ,4c SNB 95W		
Memory	4GB DDR3 1600MHz	4GB DDR3 1600MHz		
HDD (#, capacity)	1TB 7200RPM SATA3	1TB 7200RPM SATA3		
RMSD	16X DVD+/-RW SATA HH	16X DVD+/-RW SATA HH		
Graphics Adapter	Intel® HD Graphics Family	ATI Redeon HD 7570		

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 3010 DT is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})		
Idle	NA	3.5		
HDD Operating	NA	3.5		
80% TDP	NA	4.0		
ODD Operating	NA	4.3		

The Declared A-weighted Sound Pressure Level in decibels (re $2x10^{-5}$ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows¹:

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)			High-end C	d Configuration Declared Sound Pressu (LpA)			
	Table-Top Floor-Standing			Table	е-Тор	Floor- Standing		
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	24.5	18.4	18.0	19.7	23.8	19.3	18.6	18.6
HDD Operating	24.5	18.4	18.2	19.6	24.1	19.4	18.6	18.7
90% CPU	31.1	22.6	24.0	26.2	32.9	28.0	23.9	22.4
ODD Operating	43.6	34.8	36.0	38.3	43.8	38.4	35.3	34.5

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

ACOUSTIC NOISE EMISSION INFORMATION

OPTIPLEX 3010 SFF

Component	Typical Configuration	High-end Configuration	
CPU	Intel i5,3.1GHZ,4c SNB 95W Intel i5,3.1GHZ,4c SNB 95W		
Memory	4GB DDR3 1600MHz	4GB DDR3 1600MHz	
HDD (#, capacity)	1TB 7200RPM SATA3	1TB 7200RPM SATA3	
RMSD	8X DVD+/-RW SATA 12.7	8X DVD+/-RW SATA 12.7	
Graphics Adapter	Intel® HD Graphics Family	ATI Redeon HD 7570	

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 3010 SFF is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})
Idle	NA	3.4
HDD Operating	NA	3.6
80% TDP	NA	4.6
ODD Operating	NA	4.4

The Declared A-weighted Sound Pressure Level in decibels (re 2x10⁻⁵ Pa), at Operator, Bystander, and Desk Side Positions are

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)			High-end Configuration Declared Sound Pressure (LpA)				
	Table-Top		Floor-Standing		Table-Top		Floor- Standing	
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	26.1	22.7	19.0	19.2	25.9	22.6	18.8	19.1
HDD Operating	26.0	22.7	19.0	19.4	25.8	22.4	18.8	19.1
90% CPU	33.2	29.7	26.0	25.7	33.4	29.9	24.9	25.3
ODD Operating	36.6	31.1	29.7	28.4	36.7	31.1	29.3	28.6

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2